

RELIABILITY REPORT  
FOR  
MAX15006Xxxx+  
(MAX15006-MAX15007)  
PLASTIC ENCAPSULATED DEVICES

August 13, 2009

**MAXIM INTEGRATED PRODUCTS**

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<b>Approved by</b>
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## Conclusion

The MAX15006Xxxx+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX15006/MAX15007 ultra-low quiescent-current linear regulators are ideal for use in automotive and battery-operated systems. These devices operate from an input voltage of 4V to 40V, deliver up to 50mA of output current, and consume only 10 $\mu$ A of quiescent current at no load. The internal p-channel pass device keeps the quiescent current low even at full load. The MAX15007 consumes only 3 $\mu$ A current when in shutdown. The MAX15006A/MAX15007A have a fixed 3.3V output while the MAX15006B/MAX15007B have a fixed 5V output voltage. The MAX15006C/MAX15007C feature an adjustable output from 1.8V to 10V. The MAX15007 includes an enable input to turn the device on or off. All devices are short-circuit protected and include thermal shutdown. The MAX15006/MAX15007 operate over the -40°C to +125°C automotive temperature range. These devices are available in space-saving 3mm x 3mm 6-pin TDFN and 8-pin SO thermally enhanced packages.

## II. Manufacturing Information

A. Description/Function:	40V, Ultra-Low Quiescent-Current Linear Regulators in 6-Pin TDFN/8-Pin SO
B. Process:	BCD8
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Thailand
F. Date of Initial Production:	October 19, 2006

## III. Packaging Information

A. Package Type:	6-pin TDFN 3x3
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-2464
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	55°C/W
K. Single Layer Theta Jc:	8.5°C/W
L. Multi Layer Theta Ja:	42°C/W
M. Multi Layer Theta Jc:	8.5°C/W

## IV. Die Information

A. Dimensions:	68 X 74 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)  
Bryan Preeshl (Managing Director of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 48 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 22.4 \times 10^{-9}$$

$\lambda = 22.4$  F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the BCD8 Process results in a FIT Rate of 2.3 @ 25C and 39.6 @ 55C (0.8 eV, 60% UCL)

### B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

### C. E.S.D. and Latch-Up Testing

The NQ01 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX15006Xxxx+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0
<b>Moisture Testing</b> (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress</b> (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data